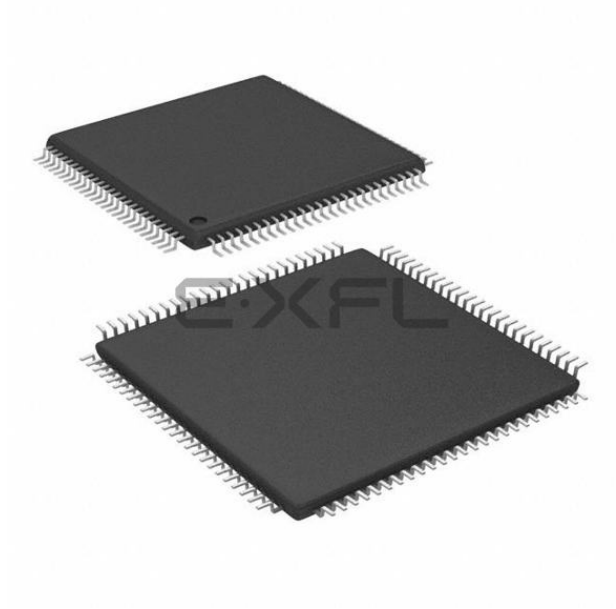
Microchip Technology - PIC32MX170F512LT-V/PF Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	85
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 48x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx170f512lt-v-pf

TABLE 5: PIN NAMES FOR 100-PIN USB DEVICES

100-PIN TQFP (TOP VIEW)

PIC32MX230F128L
PIC32MX530F128L
PIC32MX250F256L
PIC32MX550F256L
PIC32MX270F512L
PIC32MX570F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN28/RG15	36	VSS
2	VDD	37	VDD
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	AN34/RPF13/SCK3/RF13
5	AN27/PMD7/RE7	40	AN35/RPF12/RF12
6	AN29/RPC1/RC1	41	AN12/PMA11/RB12
7	AN30/RPC2/RC2	42	AN13/PMA10/RB13
8	AN31/RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	VSS
11	AN17/C1INC/RPG7/PMA4/RG7	46	VDD
12	AN18/C2IND/RPG8/PMA3/RG8	47	AN36/RPD14/RD14
13	$\overline{\text{MCLR}}$	48	AN37/RPD15/SCK4/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	VSS	50	RPF5/PMA8/RF5
16	VDD	51	USBID/RPF3/RF3
17	TMS/CTED1/RA0	52	AN38/RPF2/RF2
18	AN32/RPE8/RE8	53	AN39/RPF8/RF8
19	AN33/RPE9/RE9	54	VBUS
20	AN5/C1INA/RPB5/VBUSON/RB5	55	VUSB3V3
21	AN4/C1INB/RB4	56	D-
22	PGED3/AN3/C2INA/RPB3/RB3	57	D+
23	PGEC3/AN2/CTCMP/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	VDD
28	VREF-/PMA7/RA9	63	OSC1/CLKI/RC12
29	VREF+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AVDD	65	VSS
31	AVSS	66	RPA14/SCL1/RA14
32	AN8/RPB8/CTED10/RB8	67	RPA15/SDA1/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/SCK1/PMA15/RD10

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

5.0 INTERRUPT CONTROLLER

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Interrupt Controller"** (DS60001108) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

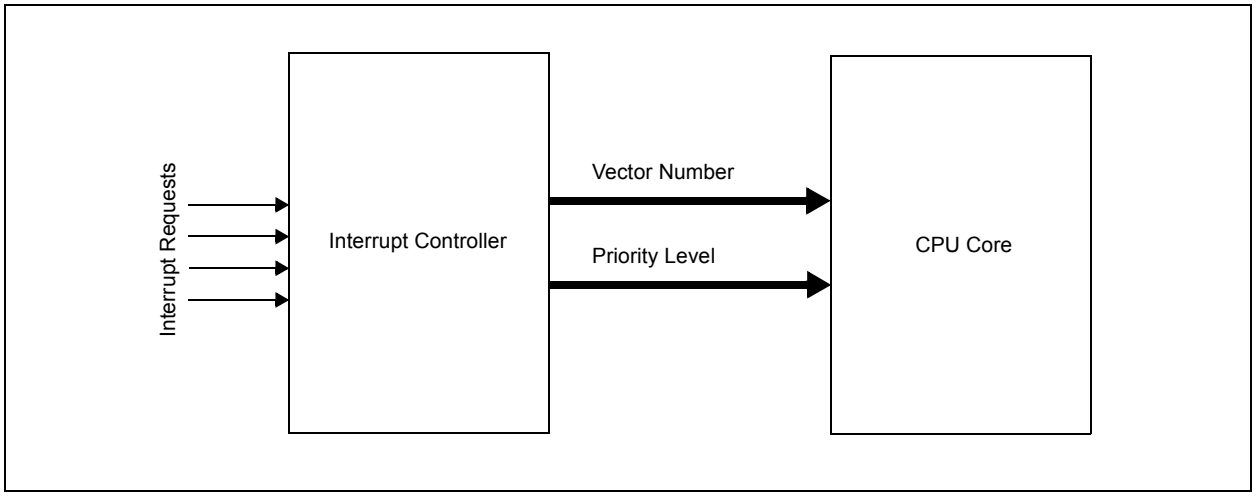
PIC32MX1XX/2XX/5XX 64/100-pin devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

The PIC32MX1XX/2XX/5XX 64/100-pin interrupt module includes the following features:

- Up to 76 interrupt sources
- Up to 46 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable subpriority levels within each priority
- Software can generate any interrupt
- User-configurable interrupt vector table location
- User-configurable interrupt vector spacing

Note: The dedicated shadow register set is not available on these devices.

FIGURE 5-1: INTERRUPT CONTROLLER MODULE BLOCK DIAGRAM



REGISTER 6-2: NVMKEY: PROGRAMMING UNLOCK REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<31:24>							
23:16	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<23:16>							
15:8	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<15:8>							
7:0	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMKEY<31:0>:** Unlock Register bits
These bits are write-only, and read as '0' on any read.

Note: This register is used as part of the unlock sequence to prevent inadvertent writes to the PFM.

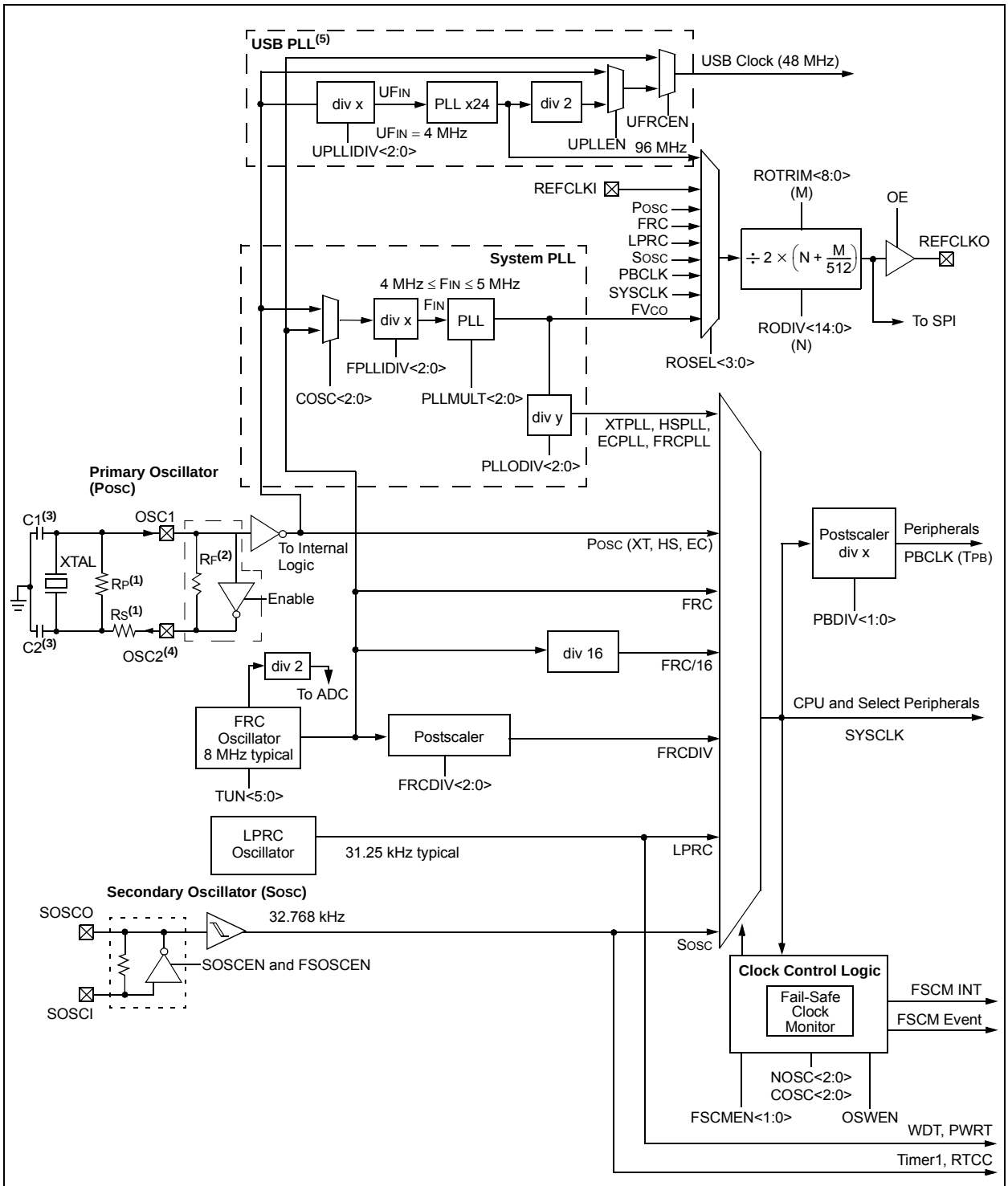
REGISTER 6-3: NVMADDR: FLASH ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMADDR<31:0>:** Flash Address bits
Bulk/Chip/PFM Erase: Address is ignored
Page Erase: Address identifies the page to erase
Row Program: Address identifies the row to program
Word Program: Address identifies the word to program

FIGURE 8-1: PIC32MX1XX/2XX/5XX 64/100-PIN FAMILY CLOCK DIAGRAM



Notes: 1. A series resistor, RS, may be required for AT strip cut crystals or eliminate clipping. Alternately, to increase oscillator circuit gain, add a parallel resistor, RP, with a value of 1 MΩ.

2. The internal feedback resistor, RF, is typically in the range of 2 MΩ to 10 MΩ.

3. Refer to **Section 6. "Oscillator Configuration"** (DS60001112) in the "*PIC32 Family Reference Manual*" for determining the best oscillator components.

4. PBCLK out is available on the OSC2 pin in certain clock modes.

5. USB PLL is available on PIC32MX2XX/5XX devices only.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 2 **UFRCEN:** USB FRC Clock Enable bit(1)
- 1 = Enable FRC as the clock source for the USB clock source
- 0 = Use the Primary Oscillator or USB PLL as the USB clock source

bit 1 **SOSCEN:** Secondary Oscillator (SOSC) Enable bit
- 1 = Enable Secondary Oscillator
- 0 = Disable Secondary Oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
- 1 = Initiate an oscillator switch to selection specified by NOSC<2:0> bits
- 0 = Oscillator switch is complete

Note 1: This bit is available on PIC32MX2XX/5XX devices only.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

TABLE 9-3: DMA CHANNEL 0 THROUGH CHANNEL 3 REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCPTR<15:0>																0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHBUSY	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FFF8
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
3260	DCH2DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
3270	DCH2CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET, and INV Registers"** for more information.

15.1 Control Registers

TABLE 15-1: INPUT CAPTURE 1 THROUGH INPUT CAPTURE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	IC1CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2010	IC1BUF	31:16	IC1BUF<31:0>																xxxx
		15:0																	xxxx
2200	IC2CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2210	IC2BUF	31:16	IC2BUF<31:0>																xxxx
		15:0																	xxxx
2400	IC3CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2410	IC3BUF	31:16	IC3BUF<31:0>																xxxx
		15:0																	xxxx
2600	IC4CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2610	IC4BUF	31:16	IC4BUF<31:0>																xxxx
		15:0																	xxxx
2800	IC5CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2810	IC5BUF	31:16	IC5BUF<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 20-2: PMMODE: PARALLEL PORT MODE REGISTER (CONTINUED)

bit 5-2 **WAITM<3:0>:** Data Read/Write Strobe Wait States bits(1)

1111 = Wait of 16 TPB
•
•
•
0001 = Wait of 2 TPB
0000 = Wait of 1 TPB (default)

bit 1-0 **WAITE<1:0>:** Data Hold After Read/Write Strobe Wait States bits(1)

11 = Wait of 4 TPB
10 = Wait of 3 TPB
01 = Wait of 2 TPB
00 = Wait of 1 TPB (default)

For Read operations:
11 = Wait of 3 TPB
10 = Wait of 2 TPB
01 = Wait of 1 TPB
00 = Wait of 0 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPBCLK cycle for a write operation; WAITB = 1 TPBCLK cycle, WAITE = 0 TPBCLK cycles for a read operation.

2: Address bits, A15 and A14, are not subject to automatic increment/decrement if configured as Chip Select CS2 and CS1.

3: These pins are active when MODE16 = 1 (16-bit mode).

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits(3)

11111111 =Alarm will trigger 256 times

•

•

•

00000000 =Alarm will trigger one time

The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

REGISTER 23-14: C1RXFn: CAN ACCEPTANCE FILTER 'n' REGISTER ('n' = 0 THROUGH 15)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	SID<10:3>							
23:16	R/W-x	R/W-x	R/W-x	U-0	R/W-0	U-0	R/W-x	R/W-x
	SID<2:0>			—	EXID	—	EID<17:16>	
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	EID<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	EID<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-21 **SID<10:0>:** Standard Identifier bits
1 = Message address bit SIDx must be '1' to match filter
0 = Message address bit SIDx must be '0' to match filter

bit 20 **Unimplemented:** Read as '0'

bit 19 **EXID:** Extended Identifier Enable bits
1 = Match only messages with extended identifier addresses
0 = Match only messages with standard identifier addresses

bit 18 **Unimplemented:** Read as '0'

bit 17-0 **EID<17:0>:** Extended Identifier bits
1 = Message address bit EIDx must be '1' to match filter
0 = Message address bit EIDx must be '0' to match filter

Note: This register can only be modified when the filter is disabled (FLTENn = 0).

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN(1)	EDGEN	EDGSEQEN	IDISSEN(2)	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **EDG1MOD:** Edge 1 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 programmed for a positive edge response
0 = Edge 1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = IC4 Capture Event is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = IC3 Capture Event is selected
1011 = IC2 Capture Event is selected
1010 = IC1 Capture Event is selected
1001 = CTED8 pin is selected
1000 = CTED7 pin is selected
0111 = CTED6 pin is selected
0110 = CTED5 pin is selected
0101 = CTED4 pin is selected
0100 = CTED3 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control edge source
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-41) in **Section 31.0 "40 MHz Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control edge source
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 23 **EDG2MOD:** Edge 2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 programmed for a positive edge response
0 = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = IC4 Capture Event is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-41) in **Section 31.0 "40 MHz Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

30.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

30.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 1)**	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode **(Note 1)**	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	600	—	ns	

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

TABLE 31-34: ADC MODULE SPECIFICATIONS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
ADC Accuracy – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	**(Note 3)**
AD21d	INL	Integral Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD22d	DNL	Differential Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Notes 2,3)**
AD23d	GERR	Gain Error	> -4	—	< 4	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD24d	EOFF	Offset Error	> -2	—	< 2	Lsb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD32b	SINAD	Signal to Noise and Distortion	55	58.5	—	dB	**(Notes 3,4)**
AD34b	ENOB	Effective Number of bits	9.0	9.5	—	bits	**(Notes 3,4)**

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

TABLE 31-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 4): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period(2)	65	—	—	ns	See Table 31-35
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	1 TAD	—	—	—	TSAMP must be ≥ 132 ns
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger(3)	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)(3)	—	0.5 TAD	—	—	—
AD63	TDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(3)	—	—	2	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

4: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

32.0 50 MHz ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX/5XX 64/100-pin Family electrical characteristics for devices operating at 50 MHz.

The specifications for 50 MHz are identical to those shown in **Section 31.0 "40 MHz Electrical Characteristics"**, with the exception of the parameters listed in this chapter.

Parameters in this chapter begin with the letter "M", which denotes 50 MHz operation. For example, parameter DC29a in **Section 31.0 "40 MHz Electrical Characteristics"**, is the up to 40 MHz operation equivalent for MDC29a.

Absolute maximum ratings for the PIC32MX1XX/2XX/5XX 64/100-pin Family 50 MHz devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias ..... -40°C to +85°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to V_{SS} **(Note 3)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 2.3V$ **(Note 3)** ..... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} < 2.3V$ **(Note 3)** ..... -0.3V to +3.6V
Voltage on D+ or D- pin with respect to V_{USB3V3} ..... -0.3V to (V_{USB3V3} + 0.3V)
Voltage on V_{BUS} with respect to V_{SS} ..... -0.3V to +5.5V
Maximum current out of V_{SS} pin(s) ..... 300 mA
Maximum current into V_{DD} pin(s) **(Note 2)** ..... 300 mA
Maximum output current sunk by any I/O pin ..... 15 mA
Maximum output current sourced by any I/O pin ..... 15 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports **(Note 2)** ..... 200 mA

Note 1: Stresses above those listed under **"Absolute Maximum Ratings"** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 32-2).

3: See the **"Device Pin Tables"** section for the 5V tolerant pins.

32.1 DC Characteristics

TABLE 32-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)(1)	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX/5XX 64/100-pin Family
MDC5	VBOR-3.6V	-40°C to +85°C	50 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for BOR values.

TABLE 32-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	Typical(3)	Max.	Units	Conditions
Operating Current (IDD) (Note 1, 2)				
MDC24	25	40	mA	50 MHz

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

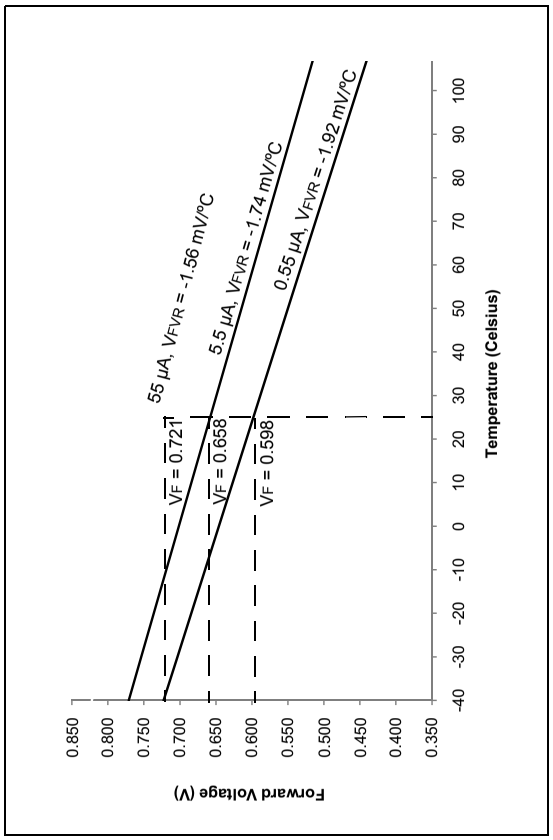
2: The test conditions for IDD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

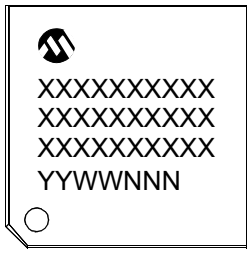
FIGURE 33-5: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



34.0 PACKAGING INFORMATION

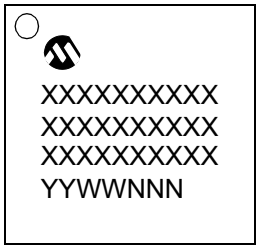
34.1 Package Marking Information

64-Lead TQFP (10x10x1 mm)

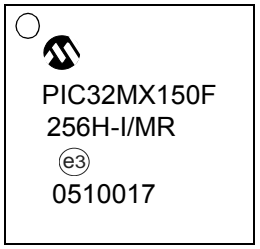


Example

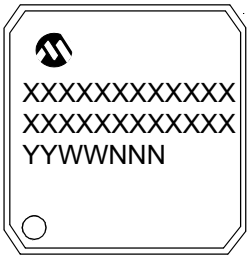
64-Lead QFN (9x9x0.9 mm)



Example

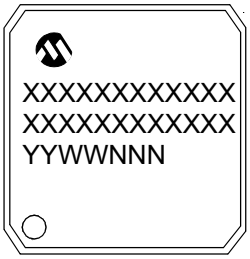


100-Lead TQFP (14x14x1 mm)



Example

100-Lead TQFP (12x12x1 mm)



Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.